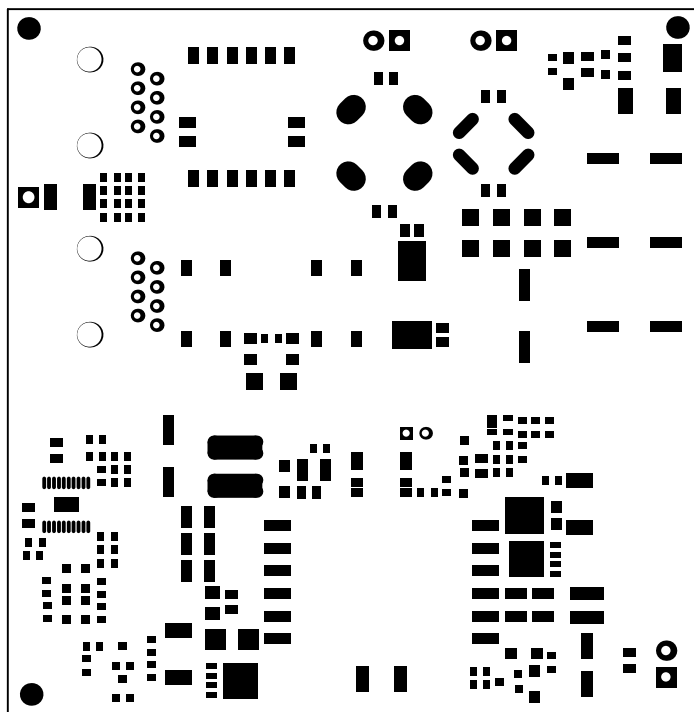
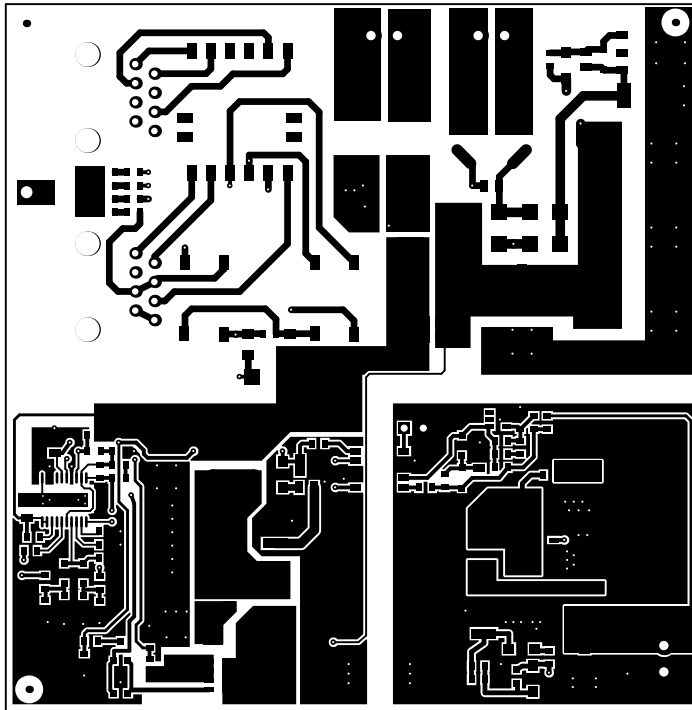


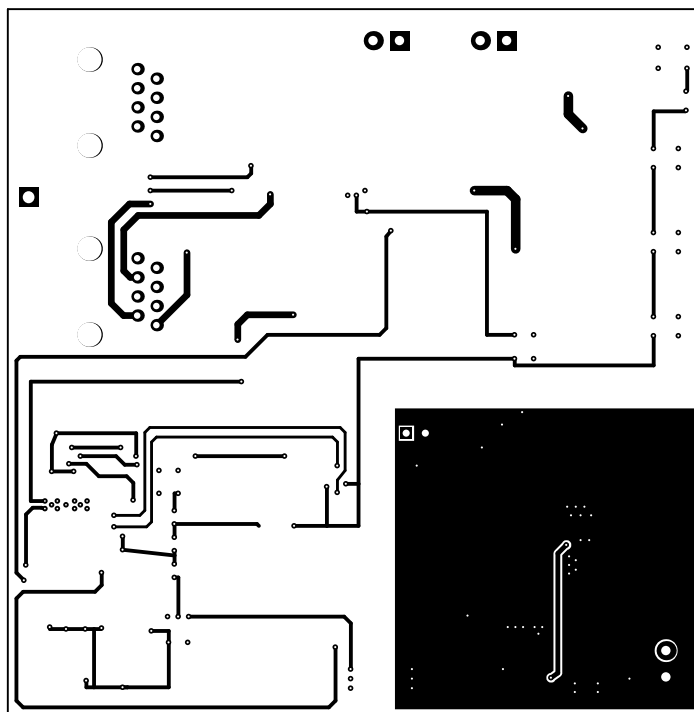
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP6659	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 1/9/2014 4:14:38 PM	TEXAS INSTRUMENTS	



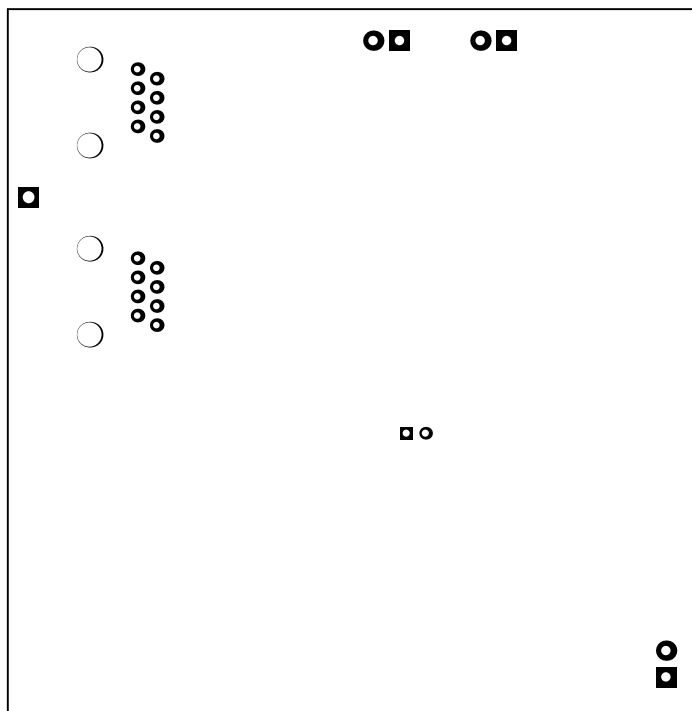
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP6659	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 1/9/2014 4:14:39 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP6659	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 1/9/2014 4:14:40 PM	TEXAS INSTRUMENTS	



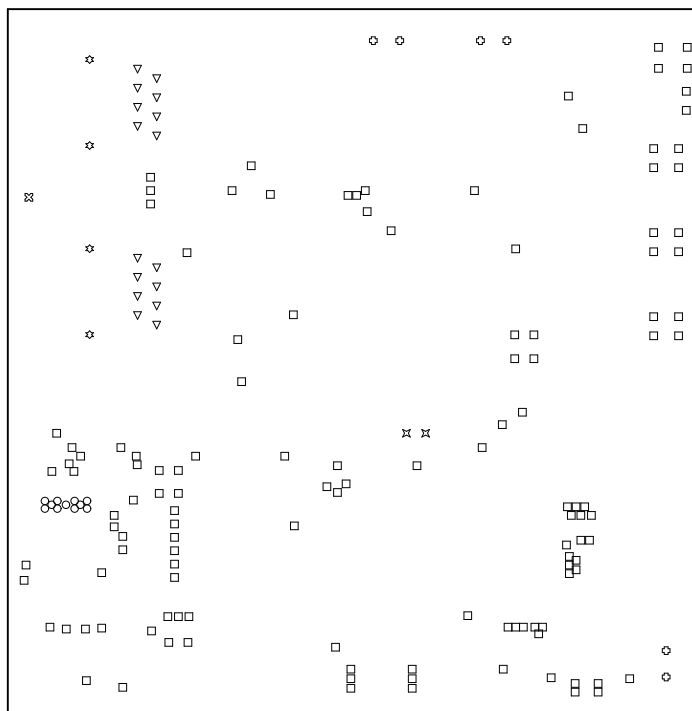
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LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 1/9/2014 4:14:40 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP6659	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 1/9/2014 4:14:41 PM	TEXAS INSTRUMENTS	



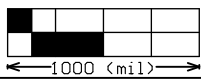
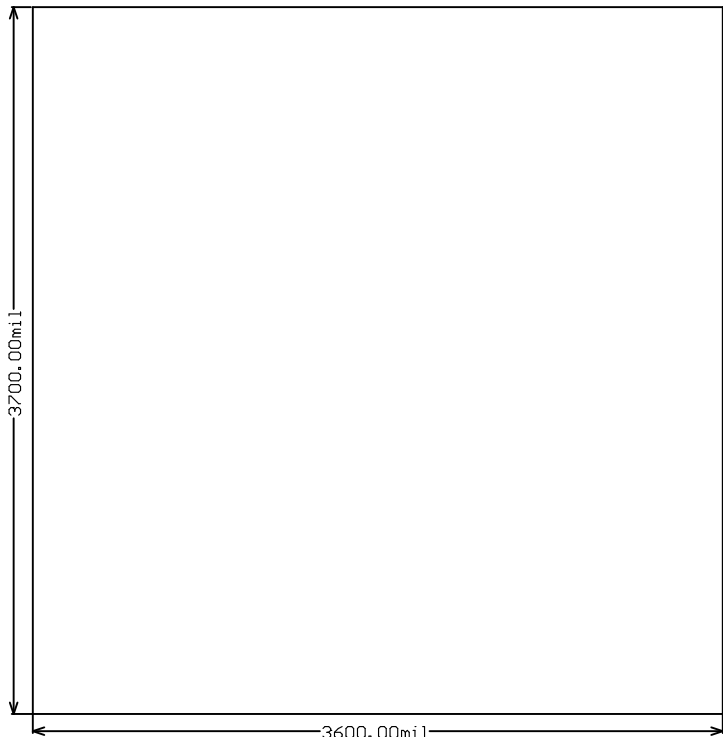
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP6659	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 1/9/2014 4:14:41 PM	TEXAS INSTRUMENTS	



Symbol	Hit Count	Tool Size	Plated	Hole Type
○	11	10mil (0.254mm)	PTH	Round
□	126	12mil (0.305mm)	PTH	Round
▽	16	35mil (0.889mm)	PTH	Round
×	2	38mil (0.965mm)	PTH	Round
⊕	6	50mil (1.27mm)	PTH	Round
⊗	1	63mil (1.6mm)	PTH	Round
*	4	128mil (3.251mm)	NPTH	Round
	166 Total			

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP6659	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 1/9/2014	4:14:42 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP6659	REV: B	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 1/9/2014 4:14:43 PM	TEXAS INSTRUMENTS	

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